



General Description

The AOZ8936DI is a multi-channel combo transient voltage suppressor array designed to protect high speed data lines such as USB3.1, USB2.0,and VBUS from damaging ESD events.

This device incorporates 2 channels for USB2.0, 4 channels for USB3.1 and 1 channel for VBUS.

The AOZ8936DI comes in a RoHS compliant and Halogen Free DFN4.1x2.0 package and is rated for -40°C to +125°C junction temperature range.

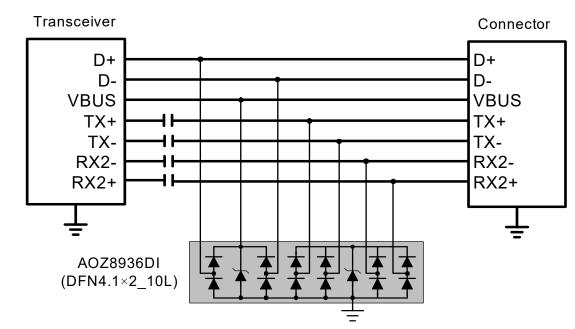
Features

- IEC61000-4-2, ESD immunity (Contact/Air):
 - ± 30/30 kV (USB 3.1)
 - ± 24/30 kV (USB 2.0)
 - ± 30/30 kV (VBUS)
- IEC61000-4-5, Surge Immunity (8/20μs):
 - ± 6 A (USB 3.1)
 - ± 4 A (USB 2.0)
 - ± 15 A (VBUS)
- Capacitance between I/O to GND:
 - 0.4pF (USB 3.1)
 - 1.75pF (USB 2.0)
 - 120pF (VBUS)

Applications

- USB 3.1/3.2 & USB 2.0
- Monitors and flat panel displays
- Set-top-box
- Notebook computers





Typical Application



Ordering Information

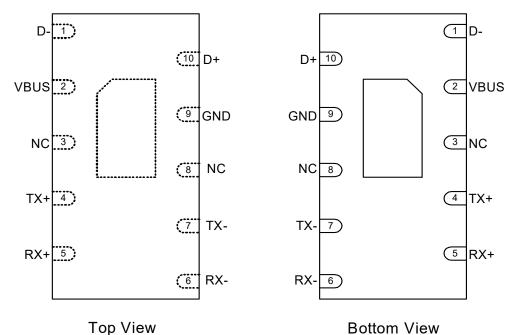
Part Number	Ambient Temperature Range	Package	Environmental			
AOZ8936DI	-40°C to +125°C	DFN4.1X2_10L	Green Product			



AOS Green Products use reduced levels of Halogens, and are also RoHS compliant.

Please visit www.aosmd.com/media/AOSGreenPolicy.pdf for additional information.

Pin Configuration



Absolute Maximum Ratings

Exceeding the Absolute Maximum ratings may damage the device.

Parameter	Rating						
	Pin 1 & Pin 10 (USB 2.0)	Pin 4 to Pin 7 (USB 3.1/3.2)	Pin 2 (VBUS)				
Storage Temperature (T _S)	-65°C to +150°C	-65°C to +150°C	-65 °C to +150°C				
ESD Rating per IEC61000-4-2, contact ⁽¹⁾	±24 kV	±30 kV	±30 kV				
ESD Rating per IEC61000-4-2, air ⁽¹⁾	±30 kV	±30 kV	±30 kV				
8/20µs Surge IEC61000-4-5	±4 A	±6 A	±15 kV				

Notes:

1. IEC 61000-4-2 discharge with C_{Discharge} = 150pF, R_Discharge = 330 Ω .

2. Human Body Discharge per MIL-STD-883, Method 3015 C_{Discharge} = 100pF, R_{Discharge} = $1.5k\Omega$.

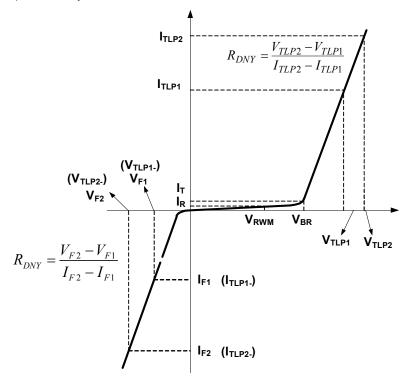
Maximum Operating Ratings

Parameter	Rating
Junction Temperature (T _J)	-40°C to +125°C



Electrical Characteristics

 $T_A = 25^{\circ}C$ unless otherwise specified. Any I/O Pin to GND.



	Pin1 & Pin 10 (D+, D- of USB 2.0)										
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units					
V _{RWM}	Reverse Working Voltage				5.5	V					
V _{BR}	Reverse Breakdown Voltage	Ι _T = 100μΑ	6.6			V					
I _R	Reverse Leakage Current	V _T = Max, V _{RWM}			1	μA					
V _F	Forward Voltage		0.7	0.85	0.95	V					
V _{CL}	Clamping Voltage ⁽³⁾⁽⁴⁾ (100ns Transmission Line Pulse)	I _{TLP} = 1A I _{TLP} = -1A		11 -1.5		V					
		I _{TLP} = 16A I _{TLP} = -16A		18 -7.5							
R _{DNY}	Dynamic Resistance ⁽³⁾⁽⁴⁾	I _{TLP} = 1A to 16A I _{TLP} = -1A to -16A			0.45 0.40	Ω					
I _{PP}	Peak Pulse Current ⁽³⁾ IEC61000-4-5 Surge 8/20μs	Any I/O Pin to GND GND to any I/O Pin			±4	А					
M	Clamping Voltage ⁽³⁾	$I_{PP} = 1A$ $I_{PP} = -1A$		10 -2		V					
V _{CL}	IEC61000-4-5 Surge 8/20µs	I _{PP} = 4A I _{PP} = -4A		12.5 -4.5							
Cj	Junction Capacitance ⁽³⁾	V _{BUS} =3.3V, f = 1MHz, Any I/O Pin to GND		1.75	2	pF					

Notes:

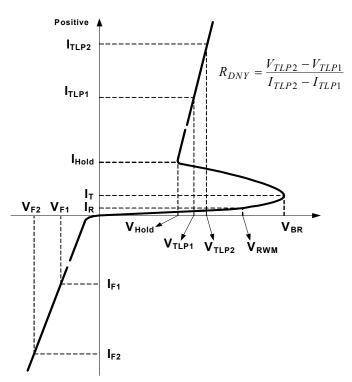
3. These specifications are guaranteed by design and characterization.

4. Measurements performed using a 100ns Transmission Line Pulse (TLP) system.



Electrical Characteristics

 $T_A = 25^{\circ}C$ unless otherwise specified. Any I/O Pin to GND.



	Pin 4 to Pin 7 (TX+, TX-, RX+, RX- of USB 3.1/3.2)									
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units				
V _{RWM}	Reverse Working Voltage				5.5	V				
V _{BR}	Reverse Breakdown Voltage	Ι _T = 100μΑ	6.6			v				
I _R	Reverse Leakage Current	V _T = Max, V _{RWM}			100	nA				
V _F	Forward Voltage		0.7	0.85	0.95	V				
V _{CL}	Clamping Voltage ⁽³⁾⁽⁴⁾	I _{TLP} = 1A I _{TLP} = -1A		1.5 -1.5		V				
•CL	(100ns Transmission Line Pulse)	I _{TLP} = 16A I _{TLP} = -16A		6 -4						
R _{DNY}	Dynamic Resistance ⁽³⁾⁽⁴⁾	I _{TLP} =1 to 16A I _{TLP} =-1 to -16A			0.30 0.20	Ω				
I _{PP}	Peak Pulse Current ⁽³⁾ IEC61000-4-5 Surge 8/20μs	Any I/O Pin to GND GND to any I/O Pin			±6	А				
Va	Clamping Voltage ⁽³⁾	I _{PP} =1A I _{PP} =-1A		2 -2		V				
V _{CL}	IEC61000-4-5 Surge 8/20μs	I _{PP} =6A I _{PP} =-6A		6 -5		v				
CJ	Junction Capacitance	V _{I/O} = 1.65V, f = 1MHz, Any I/O Pin to GND		0.4	0.6	pF				

Notes:

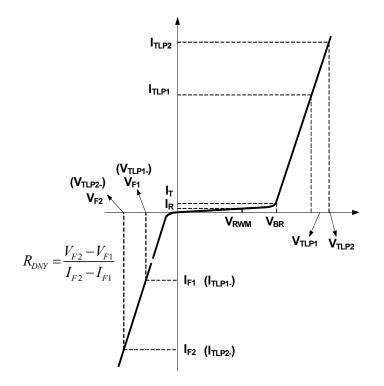
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Electrical Characteristics

 $T_A = 25^{\circ}$ C unless otherwise specified. Pin 2 to GND.



		Pin 2 (VBUS)				
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V _{RWM}	Reverse Working Voltage				5.5	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA	6.6			v
I _R	Reverse Leakage Current	V _T = Max, V _{RWM}			1	μA
V _F	Forward Voltage		0.7	0.85	0.95	V
V _{CL}	Clamping Voltage ⁽³⁾⁽⁴⁾	$I_{TLP} = 1A$ $I_{TLP} = -1A$		9 -1		V
-	(100ns Transmission Line Pulse)	I _{TLP} = 16A I _{TLP} = -16A		12 -3		
R _{DNY}	Dynamic Resistance ⁽³⁾⁽⁴⁾	I _{TLP} =1 to 16A I _{TLP} =-1 to -16A			0.20 0.13	Ω
I _{PP}	Peak Pulse Current ⁽³⁾ IEC61000-4-5 Surge 8/20µs	Any I/O Pin to GND GND to any I/O Pin			±15	A
M	Clamping Voltage ⁽³⁾	I _{PP} =1A I _{PP} =-1A		9 -1.3		V
V _{CL}	IEC61000-4-5 Surge 8/20μs	I _{PP} =15А I _{PP} =-15А		15 -3		v
CJ	Junction Capacitance	V _{I/O} = 0V, f = 1MHz, Any I/O Pin to GND		120		pF

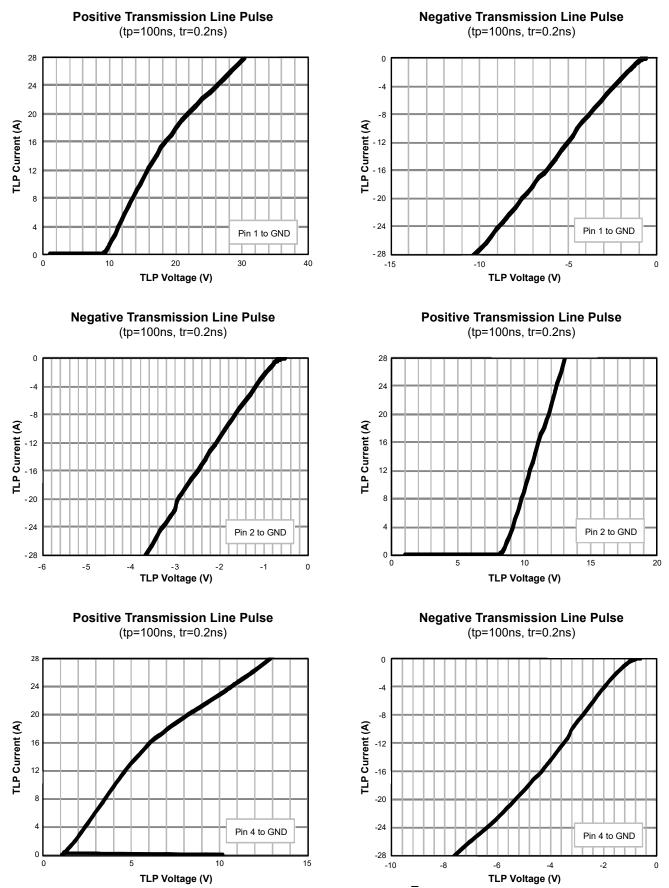
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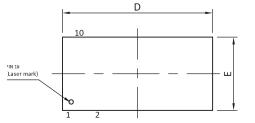
Typical Performance Characteristics

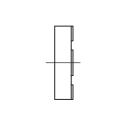


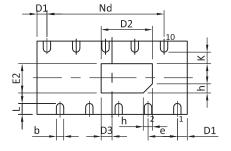
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Package Dimensions, DFN4.1x2.0-10L, EP1_S



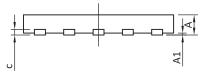




TOP VIEW

SIDE VIEW

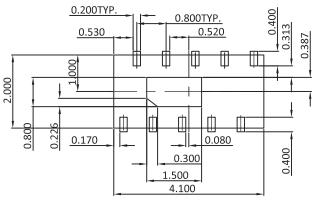




SIDE VIEW

	DIMENS	ION IN MI	LLIMETRES	DIM	ENSION IN I	NCHS		
SYMBOLS	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
А	0.45	0.50	0.55	0.018	0.020	0.022		
A1		0.02	0.05		0.001	0.002		
b	0.15	0.20	0.25	0.006	0.008	0.010		
С	0.10	0.15	0.20	0.004	0.006	0.008		
D	4.00	4.10	4.20	0.157	0.161	0.165		
D1	0.20	0.25	0.30	0.008	0.010	0.012		
D2	1.30	1.40	1.50	0.051	0.055	0.059		
D3	0.25	0.30	0.35	0.010	0.012	0.014		
е		0.80 BSC			0.031 BSC			
Nd		3.20 BSC			0.126 BSC			
E	1.90	2.00	2.10	0.075	0.079	0.083		
E2	0.70	0.80	0.90	0.028	0.031	0.035		
К	0.20			0.008				
L	0.25	0.30	0.35	0.010	0.012	0.014		
h	0.15	0.20	0.25	0.006	0.008	0.010		

LAND PATTERN RECOMMENDATIONS



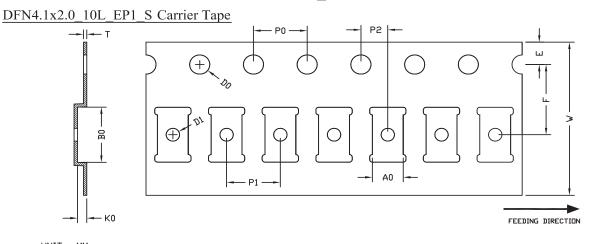
UNIT: mm

NOTES

1. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

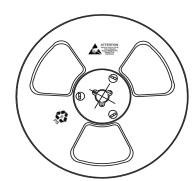


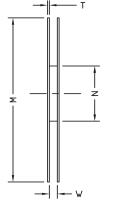
Tape and Reel Dimensions, DFN4.1x2.0-10L, EP1_S

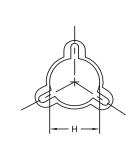


UNII: MM												
PACKAGE	A0	BO	К0	DO	D1	W	E	F	P0	P1	P2	т
DFN4.1×2.0	2.30 ±0.05	4.30 ±0.05	0.70 ±0.05	1.50 +0.1 -0.0	1.00 Min.	12.00 +0.30 -0.10	1.75 ±0.10	5.50 ±0.05	4.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.25 ±0.03

DFN4.1x2.0_10L_EP1_S_Reel



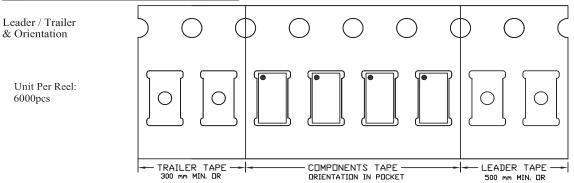




UNIT: MM

TAPE SIZE	REEL SIZE	м	N	W	Т	н	к	S	G	R	V
12 mm	ø329	Ø329.00 ±1.00	ø100.00 ±1.00	12.80 ±1.00	2.00 ±0.30	ø13.30 ±0.30					

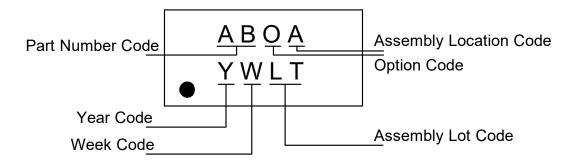
DFN4.1x2.0_10L_EP1_S Package Tape





Part Marking

AOZ8936DI (DFN4.1x2.0_10L)



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